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(54) Title: CIRCUIT SUBSTRATE

(57) Abstract: The present invention may provide a circuit substrate containing an insulating resin layer, wherein said insulating resin layer contains polyimide and a clay mineral, said insulating resin layer has an elastic modulus of not less than 0.3 GPa and not more than 30 GPa at 450 degrees C and said insulating resin layer with a thickness of 20 micrometers has a light transmittance of not less than 40 % at a wavelength of 650 nm.